

# Board Stack Report

Stack Up		Layer Stack			
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1		Top Paste			
2		Top Overlay			
3		Top Solder	Solder Resist	0.40mil	3.5
4		Top Layer	Copper	1.40mil	
5		Dielectric1	FR-4	12.60mil	4.8
6		Mid-Layer 2	Copper	1.40mil	
7		Dielectric3	FR-4	12.60mil	4.8
8		Mid-Layer 1	Copper	1.40mil	
9		Dielectric2	FR-4	12.60mil	4.8
10		Bottom Layer	Copper	1.40mil	
11		Bottom Solder	Solder Resist	0.40mil	3.5
12		Bottom Overlay			
13		Bottom Paste			
Height : 44.20mil					